



SMD Auto X8G HT150C Flex, Ceramic, 270 pF, 1%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, Automotive Grade, 1206, 1.5 mm



General Information	
Series	SMD Auto X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable, Automotive Grade
Features	High Temperature, Ultra-Stable, Automotive Grade
RoHS	Yes
Termination	Flexible Termination
Marking	No
Qualifications	AEC-Q200
AEC-Q200	Yes
Typical Component Weight	15 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1206
L	3.3mm +/-0.4mm
W	1.6mm +/-0.35mm
Т	0.78mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm

S	1.5mm MIN
В	0.6mm +/-0.25mm
Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape

4000

Packaging Quantity

Specifications	
Capacitance	270 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	1%
Voltage DC	250 VDC
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and	d
we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the	ıe
requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by u	S
with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.	

Generated 05/03/2025 © 2006 - 2025 YAGEO